CLAIMS

1. Method to produce conductive rods (210,310) on an electronic component (200,300) comprising one or more conductive blocks (202,302), each of the conductive rods being in at least partial contact with a block of the electronic component, comprising the following steps:

- deposition of a conductive base (105,305) on said component,
- deposition of a masking layer (106, 206, 306) on said conductive base (105,305),
- formation in said masking layer of a plurality of holes (207, 307, 107), at least one conductive block of said conductive blocks being located opposite one or more holes,
- filling of holes with a conductive material base, by means of electrolysis and using the conductive base as an electrode, in order to form the conductive rods (210,310),
- removal of the masking layer (206,306).

2. Method to produce conductive rods (210,310) on an electronic component (200,300) according to claim 1, wherein, in the formation step in said masking layer of a plurality of holes (207, 307, 107), at least one conductive block of said conductive blocks is located opposite one or more holes, at least one hole of said holes has none of said conductive blocks opposite it, the method also comprising, after

the formation step of the plurality of holes and prior to the filling by means of electrolysis:

- etching of the conductive base (305) via the holes (307).

3. Method to produce conductive rods (210,310) on an electronic component (200,300) according to claim 1, wherein, in the formation step in said masking layer of a plurality of holes (207, 307, 107), at least one conductive block of said conductive blocks is located opposite one or more holes, at least one hole of said holes has none of said conductive blocks opposite it, the method also comprising: between the deposition of the conductive base (105,305) on said component and the deposition of the masking layer (106, 206, 306) on said conductive base, the following steps:

- deposition of a thin insulating layer (103) on the conductive base (105),

- formation of a plurality of openings (104) in said thin insulating layer, each opening being located opposite a conductive block.

4. Method according to claim 3, characterised in that, of the plurality of holes (107) formed in the hole formation step in the masking layer, some holes (107a) reveal the thin insulating layer (103), some other holes (107b) reveal the conductive base.

5. Method to produce conductive rods (110) on an electronic component (100) according to claim 1,

wherein, in the formation step in said masking layer of a plurality of holes (107), each hole is at least partially located opposite a conductive block.

6. Method according to claim 5, also comprising, after the formation step in said masking layer of a plurality of holes and prior to the filling step by means of electrolysis:

- etching of the conductive base via the holes.

7. Method according to any of claims 1 to 6, said masking layer comprising at least one photosensitive polymer layer.

8. Method according to any of claims 1 to 7, wherein said conductive blocks are inserted in a passivation layer (304) coating said electronic components.

9. Method according to any of claims 1 to 8, the conductive base (105,305) being formed from a stack of at least two different conductive layers.

10. Method according to any of claims 1 to 9, also comprising after the masking layer removal step, an at least partial conductive base removal or selective conductive base etching step.

11. Method according to any of claims 1 to 10, also comprising after the filling step by means of

electrolysis, an additional noble metal-based chemical deposition step on the conductive rods (310).

12. Microelectronic device liable to be obtained by means of the method according to any of claims 1 to 11.